



RoHS & Halogen Free & REACH Compliance.

SPECIFICATION FOR APPROVAL

Customer : _____

Customer P/N : _____

Drawing No : _____

Quantity : _____ **Pcs.** **Date :** _____

Chilisin P/N : _____ **BTLDDK16082G4S1AR0**

SPECIFICATION ACCEPTED BY:	
COMPONENT ENGINEER	
ELECTRICAL ENGINEER	
MECHANICAL ENGINEER	
APPROVED	
REJECTED	

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Drawn by Jason	Checked by CF	Approved by Derek
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APPLICATION
Dual-band WLAN.

FEATURES

1-1 Compact Size

Miniaturized SMD packaged in low profile and lightweight.

1-2 Low loss

Low insertion loss, high attenuation.

1-3 High Soldering Heat Resistance

High quality termination allows both flow and re-flow soldering methods to be applied.

1-4 Characteristics

Eliminate noise over a wide frequency range. Idea for high frequency and space limited designs.

1-5 Available in tape and reel packaging for automatic mounting

PRODUCT IDENTIFICATION

BTLD DK 1608 ###xx AR 0
 ① ② ③ ④ ⑤ ⑥

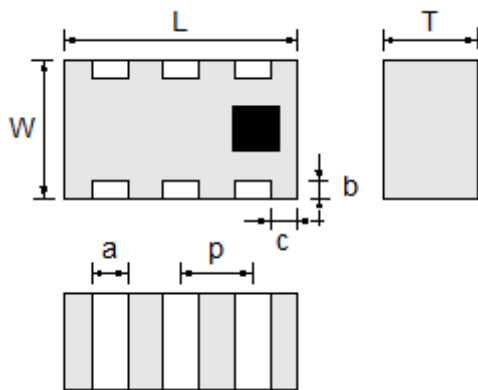
- ① Product Code
- ② Customer Code
- ③ Dimension Code
- ④ Series Type (### represents center frequency and xx represents material type)
- ⑤ Design Code
- ⑥ Version Code

ELECTRICAL REQUIREMENTS

Part No.	Item	Frequency Range	Insertion Loss	VSWR	Stop-Band Attenuation
BTLDDK16082G4S1AR0	Low Band	2400~2500 MHz	0.45 dB max. at 25deg C	2.0 max	21 dB min. at 4800 ~ 5000 MHz
			0.6dB max. at -40 ~ +85deg C		23 dB min. at 5000 ~ 5950 MHz
					30 dB min. at 7200 ~ 7500 MHz
	High Band	4900~5950 MHz	0.6 dB max. at 25deg C	2.0 max	27 dB min. at 824 ~ 2170 MHz
			0.75dB max. at -40 ~ +85deg C		30 dB min. at 2400~2500 MHz
					32 dB min. at 9800~11900 MHz
Common	2400~2500 MHz 4900~5950 MHz	----	2.0 max	----	

Operating Temperature Range: -40~85°C
Power Capacity: 3W max.

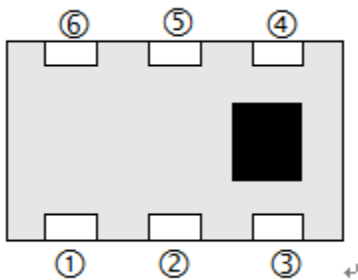
PRODUCT DIMENSION



L	W	T	a
1.6±0.1	0.8±0.1	0.6±0.1	0.2±0.1
b	c	p	
0.15±0.1	0.2+0.1/-0.15	0.5±0.05	

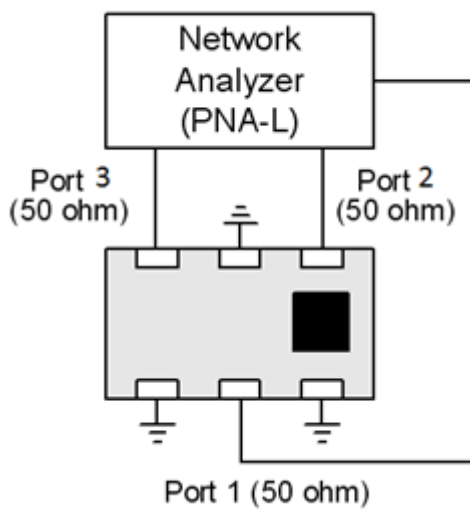
NOTE : Dimensions in mm

TERMINAL CONFIGURATION



- ① GND
- ② Common Port
- ③ GND
- ④ Low Frequency Port
- ⑤ GND
- ⑥ High Frequency Port

MEASURING DIAGRAM

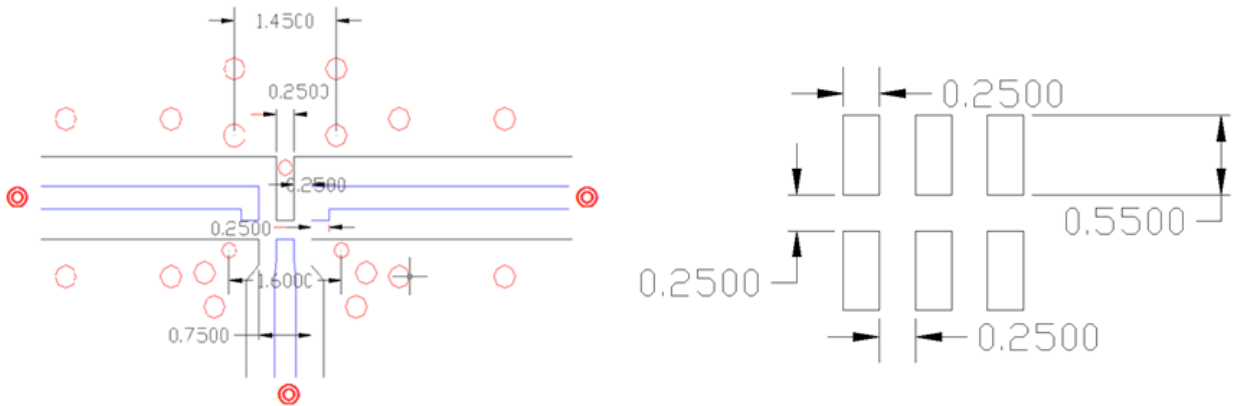


Test Instrument:
Agilent N5230A Network Analyzer
or equivalent



ISO9001 & ISO14001 & TS16949 **CHILISIN ELECTRONICS CORP.**

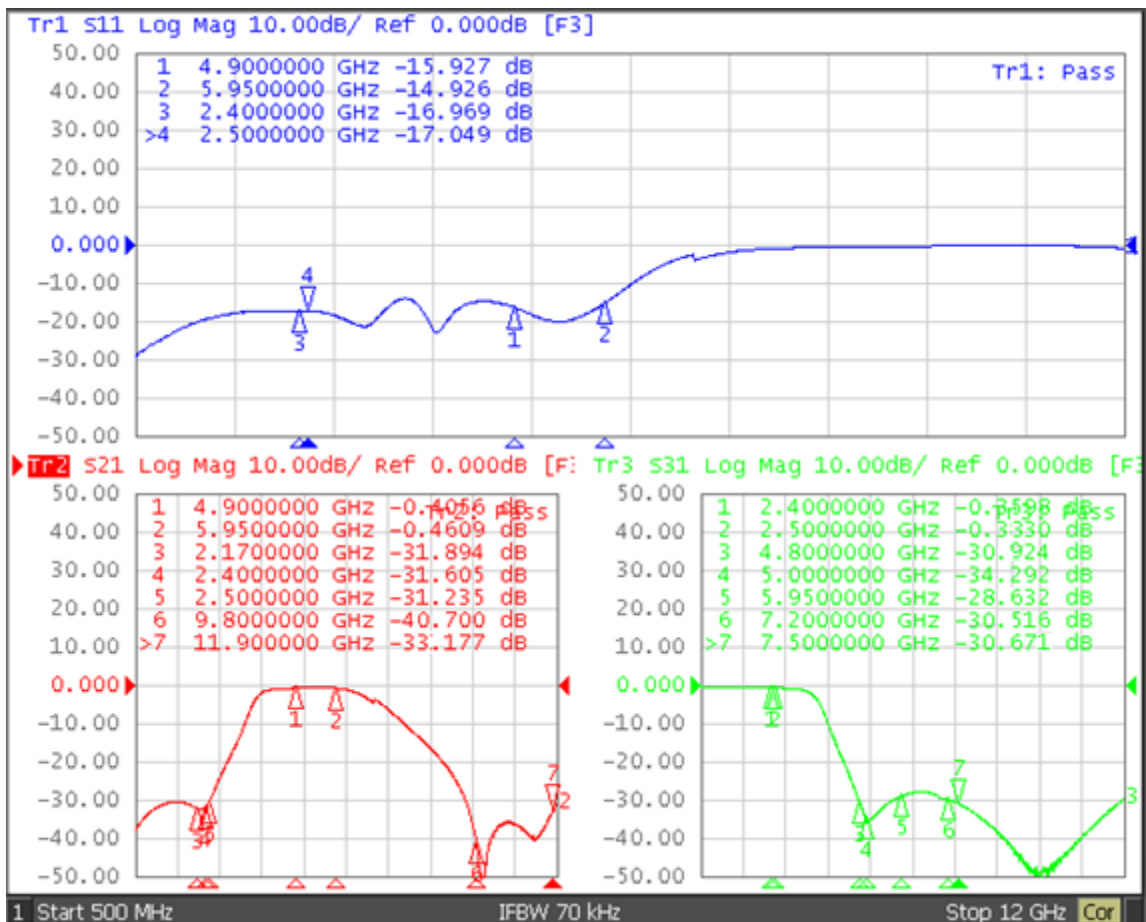
RECOMMENDED PCB LAYOUT AND LAND PATTERN



unit: mm

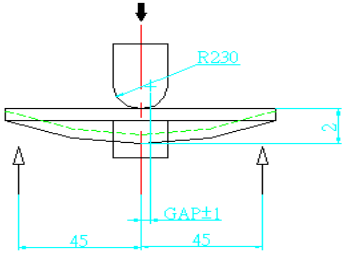
⊙ Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

ELECTRICAL CHARACTERISTICS (T=25°C)



RELIABILITY TEST

Mechanical Test

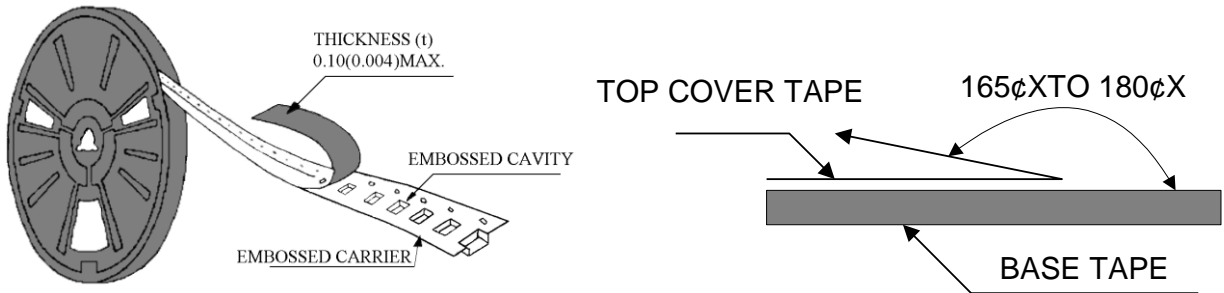
Item	Specification	Test Condition
Vibration	No apparent damage	10 Hz/min~55 Hz/min~10 Hz/min vibration frequency with 1.5 mm amplitude for two hours in x, y, z directions
Drop shock	No apparent damage	Dropped onto printed circuit board from 100cm height three times in x, y, z directions. The terminals shall be protected.
Soldering heat resistance	No apparent damage	Preheating temperature : $150\pm 10^{\circ}\text{C}$ Preheating time : 1 to 2 minutes Solder bath temperature : $260\pm 5^{\circ}\text{C}$ Bathing time : 5 ± 0.5 seconds
Bending test onto printed circuit board	No apparent damage	Solder specimen LTCC components on the test printed circuit board (L: 100 x W: 40 x T: 1.6mm) in appended recommended PCB pattern. Apply the load in direction of the arrow until bending reaches 2 mm.  Unit: mm
Solderability	No apparent damage	The dipped surface of the terminal shall be at least 75% covered with solder after dipped in solder bath of $245\pm 5^{\circ}\text{C}$ for 3 ± 0.5 seconds.

Environment Test

Item	Specification	Test Condition
Thermal shock	No apparent damage Fulfill the electrical spec. after test	$-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$ for 100 cycles each cycle being 30 min
Humidity resistance	No apparent damage Fulfill the electrical spec. after test	$85\pm 2^{\circ}\text{C}$, 80~90% R.H. for 500 hours
High temperature resistance	No apparent damage Fulfill the electrical spec. after test	$+85\pm 2^{\circ}\text{C}$ for 500 hours
Low temperature resistance	No apparent damage Fulfill the electrical spec. after test	$-40\pm 3^{\circ}\text{C}$ for 500 hours

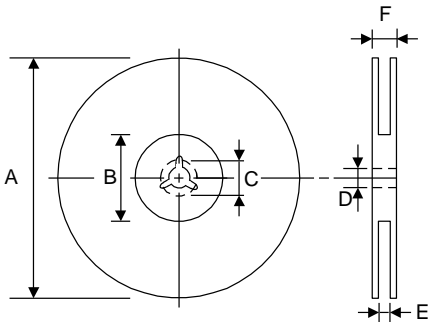
PACKAGING FOR SMC

Peel-off force



The force for peeling off cover tape is 10 grams in the arrow direction.

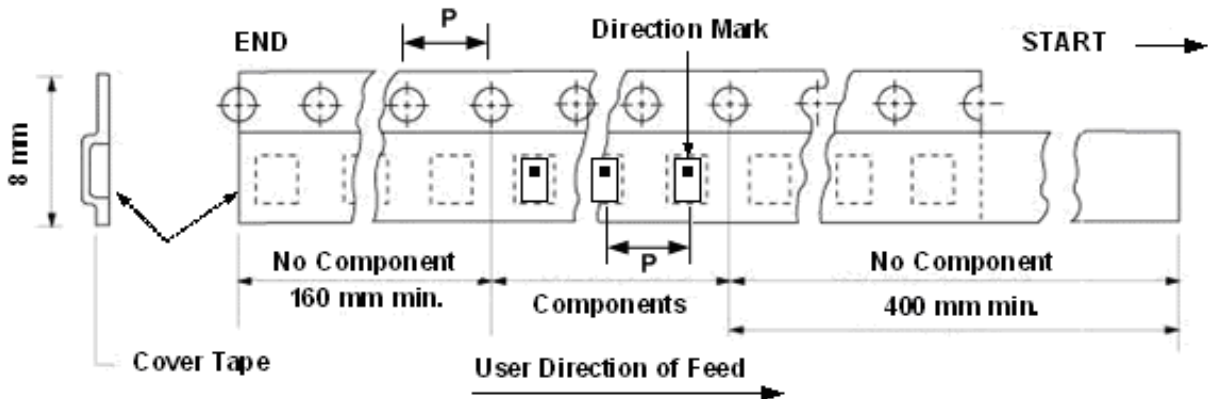
Dimension (Unit: mm)



TYPE	A	B	C	D	E	F
8 mm	178±1	60+0.5 -0	-	13 ±0.2	9 ±0.5	12 ±0.5
12 mm	178±0.3	60 ±0.2	19.3 ±0.1	13.5 ±0.1	13.6 ±0.1	-

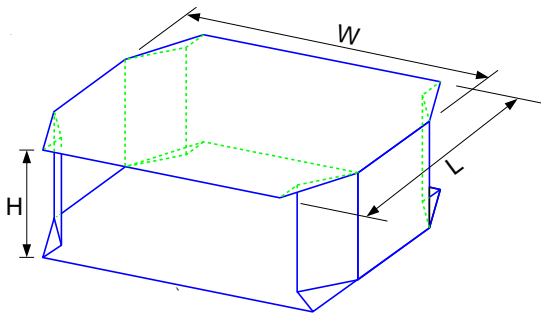
Taping quantity

SERIES	5824 5724	5320 5220	4532	4516	3225	3216 2520	2012 1608	1005 0605
PCS/Reel	5000	3000	1000	2000	2500	3000	4000	10000



P=4 mm

TAPE PACKING CASE



Unit:cm

No. of Reels	W	L	H
2	18±0.5	18±0.5	2.4±0.2
3	18±0.5	18±0.5	3.6±0.2
4	18±0.5	18±0.5	4.8±0.2
5	18±0.5	18±0.5	6.0±0.2

OPERATION TEMPERATURE

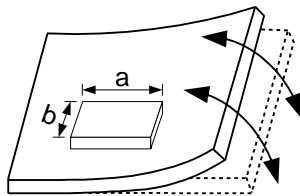
-40°C~+85°C

STORAGE CONDITION

The temperature should be within -20 ~ 35°C and humidity should be less than 75% RH. The product should be used within 6 months from the time of delivery.

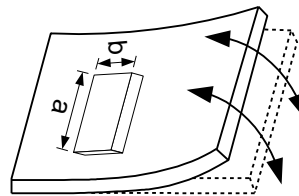
ATTENTION REGARDING PCB BENDING

- (a) PCB shall be designed so that products are not subjected to the mechanical stress for board warpage. Product shall be located in the sideways direction to the mechanical stress.



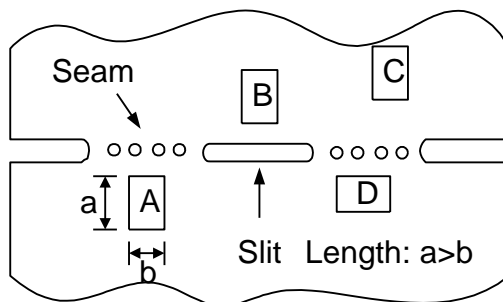
(Poor example)

Length: $a > b$

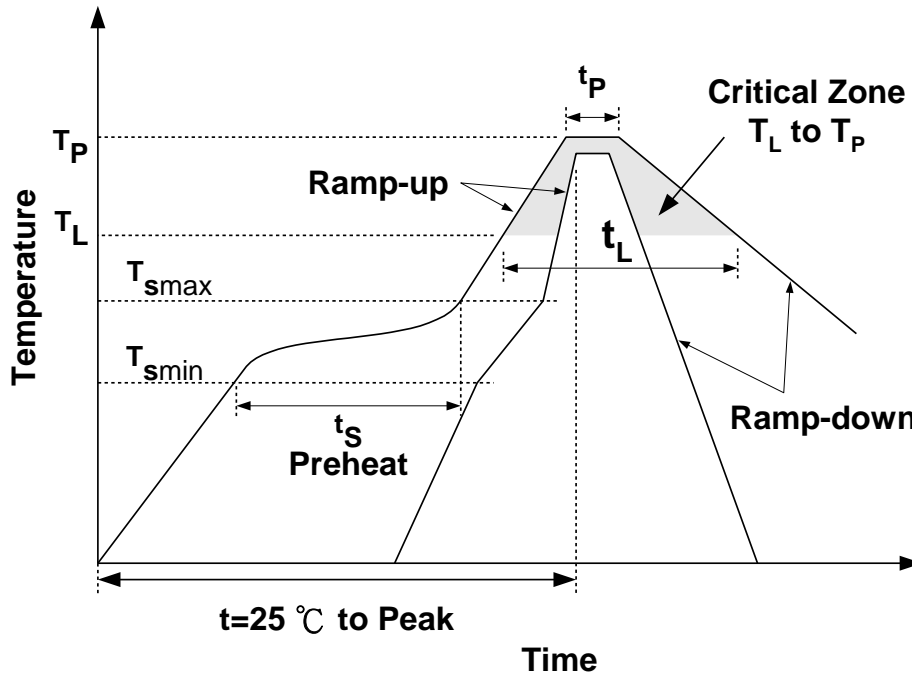


(Good example)

- (b) Products (A,B,C,D) shall be located carefully so that products are not subjected to the mechanical stress due to warping the board. Because they may be subjected to the mechanical stress in order of $A > C > B \approx D$.



Recommended Reflow Soldering Profile



Profile Feature		Sn-Pb	Pb-Free
Preheat	ts	60~120 seconds	60~180 seconds
	Tsmmin	100°C	150°C
	Tsmax	150°C	200°C
Average ramp-up rate (Tsmax to TP)		3°C/second max.	3°C/second max.
Time main above	Temperature (TL)	183°C	217°C
	Time (tL)	60~150 seconds	60~150 seconds
Peak temperature (TP)		230°C	250~260°C
Time within 5°C of actual peak temperature (tP)		10 seconds	10 seconds
Ramp-down rate		6°C/sec max.	6°C/sec max.
Time 25°C to peak temperature		6 minutes max.	8 minutes max.

NOTES

The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.